



Product Change Notification - LIAL-06FXHO065

Date:

12 Nov 2018

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers

Affected CPNs:**Notification subject:**

CCB 3250 Cancellation Notice: For the qualification of palladium coated copper with gold flash (CuPdAu) bond wire and G631HQ mold compound in selected products of the 160K wafer technology available in 64L TQFP package at ANAP assembly site.

Notification text:**PCN Status:**

Cancellation notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

This change would have affected selected products of the 160K wafer technology available in 64L TQFP package assembled at ANAP assembly site using gold (Au) bond wire and G700L mold compound material.

Description of Change:

This qualification was originally performed to qualify palladium coated copper with gold flash (CuPdAu) bond wire and G631HQ mold compound in selected products of the 160K wafer technology available in 64L TQFP package at ANAP assembly site.

Impacts to Data Sheet:

Not applicable

Change Impact:

Not applicable

Reason for Change:

Microchip has decided not to qualify palladium coated copper with gold flash (CuPdAu) bond wire and G631HQ mold compound in selected products of the 160K wafer technology available in 64L TQFP package at ANAP assembly site.

Change Implementation Status:

Not applicable

Method to Identify Change:

Not applicable

Revision History:

February 12, 2018: Issued initial notification.

March 21, 2018: Revised this initial notification to be issued to all affected customers.

November 12, 2018: Issued cancellation notice for the proposed qualification of palladium coated copper with gold flash (CuPdAu) bond wire and G631HQ mold compound in selected products of the 160K wafer technology available in 64L TQFP package at ANAP assembly site.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):



Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers(CPN)

DSPIC30F6011-20E/PF

DSPIC30F6011-20I/PF

DSPIC30F6011-30I/PF

DSPIC30F6012-20I/PF

DSPIC30F6012-30I/PF